

Features

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

Product Summary

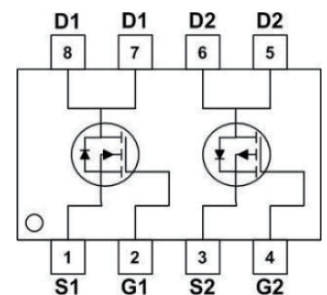
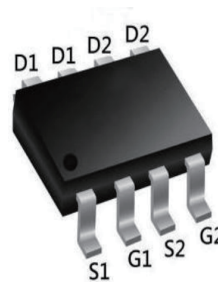
BVDSS	RDSON	ID
40V	17mΩ	8.5A
-40V	39mΩ	-7.5A

Description

THE 4614 is the highest performance trench N-ch and P-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

THE 4614 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

SOP8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Max. N-Channel	Max. P-Channel	Units	
V _{DSS}	Drain-Source Voltage	40	-40	V	
V _{GSS}	Gate-Source Voltage	±20	±20	V	
I _D	Continuous Drain Current	T _A = 25°C	8.5	-7.5	A
		T _A = 100°C	5.2	-3.9	A
I _{DM}	Pulsed Drain Current ^{note1}	32	-24	A	
E _{AS}	Single Pulsed Avalanche Energy ^{note2}	13	17.6	mJ	
P _D	Power Dissipation	T _A = 25°C	2	3.2	W
R _{θJA}	Thermal Resistance, Junction to Ambient	62.5	39	°C/W	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150		°C	

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified) N-Channel

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=40V, V_{GS}=0V$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance <small>note3</small>	$V_{GS}=10V, I_D=8A$	-	17	22	m Ω
		$V_{GS}=4.5V, I_D=5A$	-	25	35	m Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=20V, V_{GS}=0V,$ $f=1.0MHz$	-	633	-	pF
C_{oss}	Output Capacitance		-	67	-	pF
C_{rss}	Reverse Transfer Capacitance		-	58	-	pF
Q_g	Total Gate Charge	$V_{DS}=20V, I_D=8A, V_{GS}=10V$	-	12	-	nC
Q_{gs}	Gate-Source Charge		-	3.2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	3.1	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=20V, R_L=2.5\Omega$ $V_{GS}=10V, R_{REN}=3\Omega$	-	4	-	ns
t_r	Turn-on Rise Time		-	3	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	15	-	ns
t_f	Turn-off Fall Time		-	2	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	8.5	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	32	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=8A$	-	-	1.2	V

Note :

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition : $T_J=25^\circ\text{C}, V_{DD}=20V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=7.2A$
 $T_J=25^\circ\text{C}, V_{DD}=-20V, V_G=-10V, L=0.5mH, R_g=25\Omega, I_{AS}=8.4A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified) P-Channel

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D = -250\mu A$	-40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -40V, V_{GS}=0V$	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D = -250\mu A$	-1	-1.6	-2.5	V
$R_{DS(on)}$ <small>note3</small>	Static Drain-Source on-Resistance	$V_{GS} = -10V, I_D = -6A$	-	39	53	m Ω
		$V_{GS} = -4.5V, I_D = -4A$	-	58	81	m Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -20V, V_{GS}=0V,$ $f=1.0MHz$	-	860	-	pF
C_{oss}	Output Capacitance		-	87	-	pF
C_{rss}	Reverse Transfer Capacitance		-	70	-	pF
Q_g	Total Gate Charge	$V_{DS} = -20V, I_D = -6A,$ $V_{GS} = -10V$	-	13	-	nC
Q_{gs}	Gate-Source Charge		-	3.8	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	3.1	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -20V, R_L = 2.3\Omega$ $V_{GS} = -10V, R_{REN} = 6\Omega$	-	7.5	-	ns
t_r	Turn-on Rise Time		-	5.5	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	19	-	ns
t_f	Turn-off Fall Time		-	7	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-7.5	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-24	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S = -6A$	-	-	-1.2	V

Note :

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition : $T_J = 25^\circ\text{C}, V_{DD} = 20V, V_G = 10V, L = 0.5mH, R_g = 25\Omega, I_{AS} = 7.2A$
 $T_J = 25^\circ\text{C}, V_{DD} = -20V, V_G = -10V, L = 0.5mH, R_g = 25\Omega, I_{AS} = -8.4A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

N-Channel Typical Performance Characteristics

Figure 1: Typical Output Characteristics

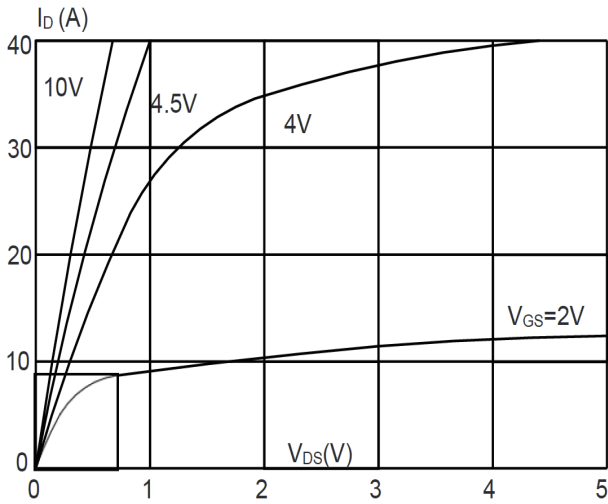


Figure 2: Typical Transfer Characteristics

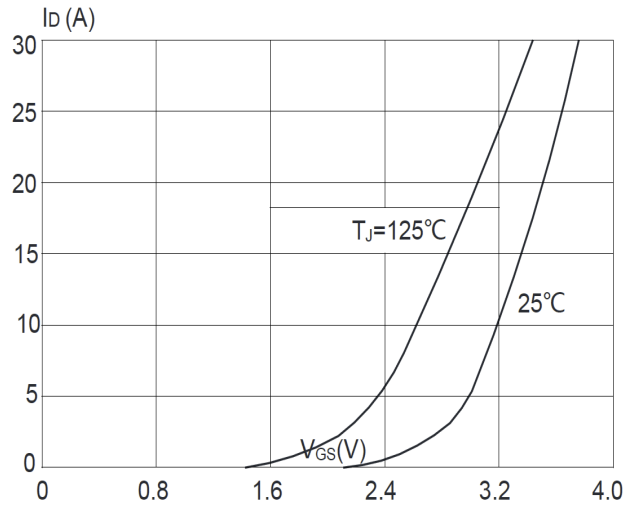


Figure 3: On-resistance vs. Drain Current

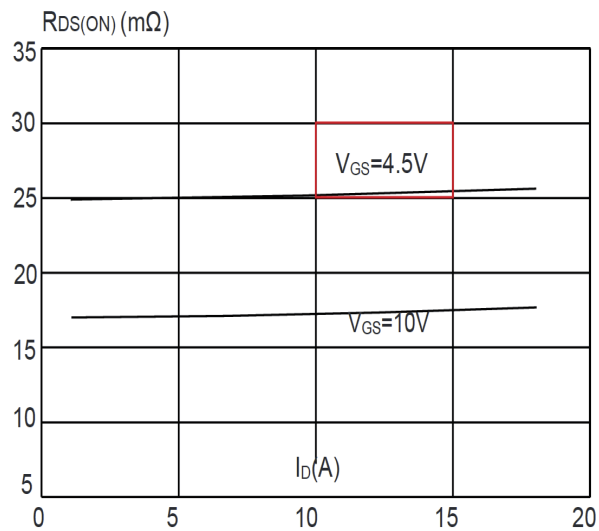


Figure 4: Body Diode Characteristics

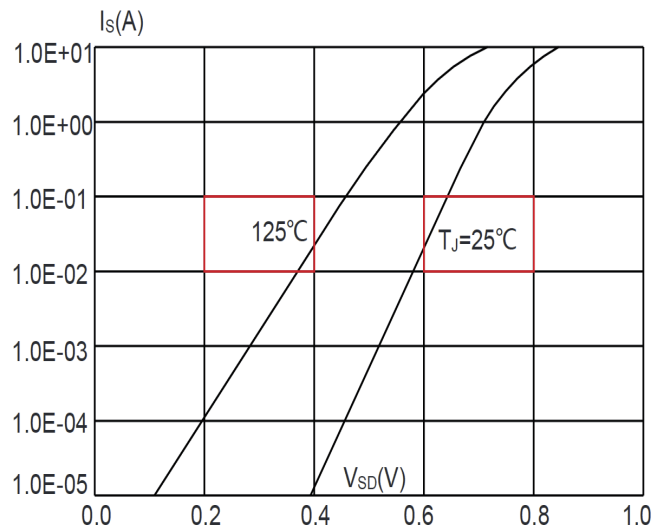


Figure 5: Gate Charge Characteristics

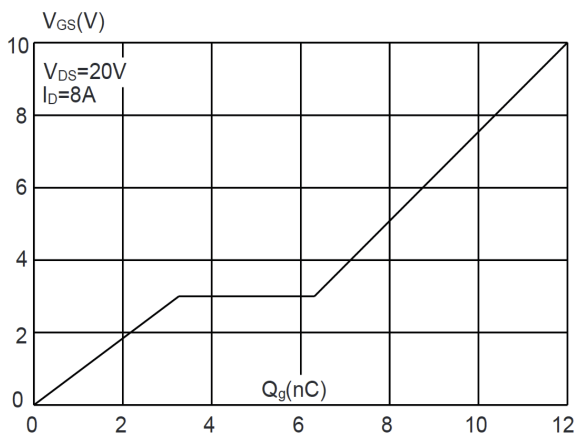
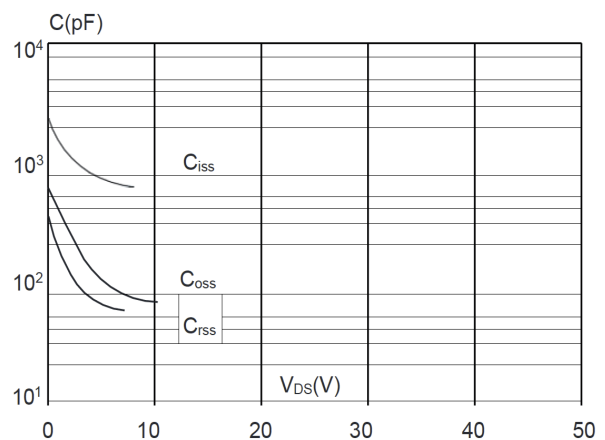


Figure 6: Capacitance Characteristics



N-Channel Typical Performance Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

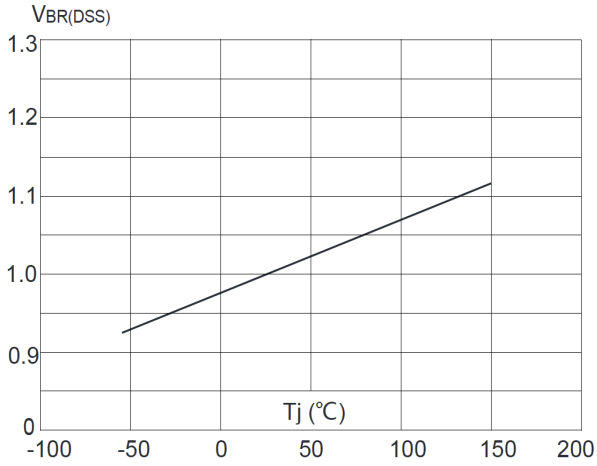


Figure 8: Normalized on Resistance vs. Junction Temperature

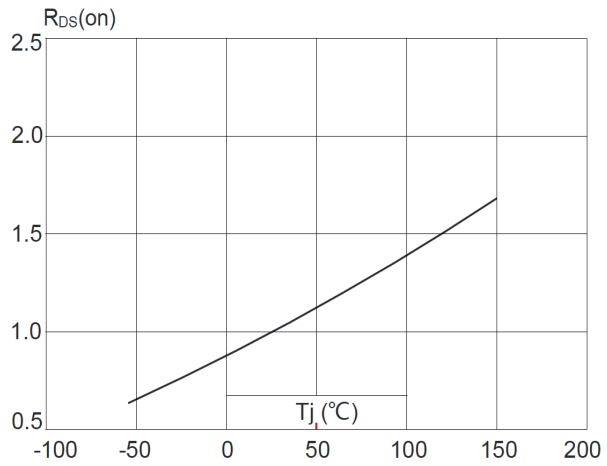


Figure 9: Maximum Safe Operating Area

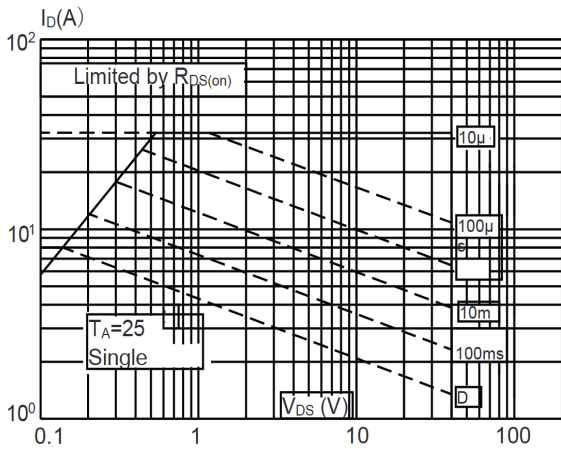


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

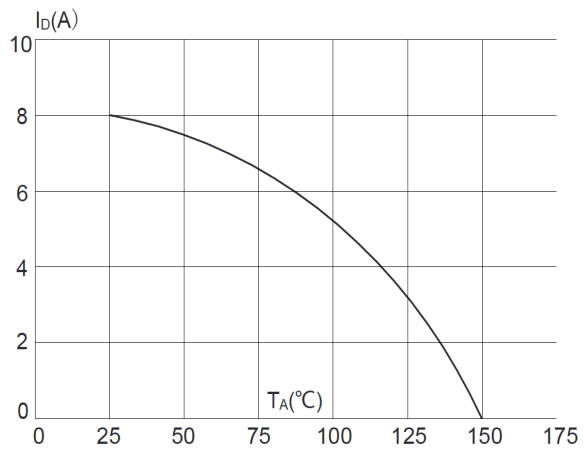
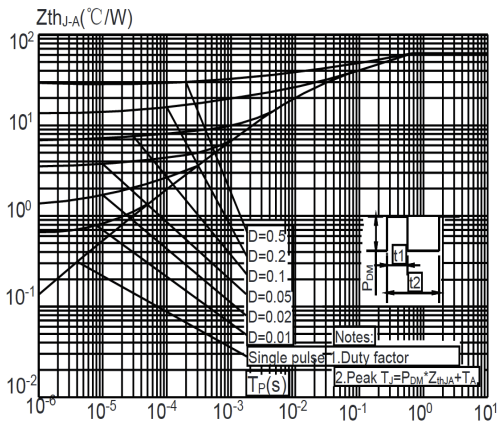


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

Transient Thermal Impedance, Junction-to-Ambient



P-Channel Typical Performance Characteristics

Figure 1: Typical Output Characteristics

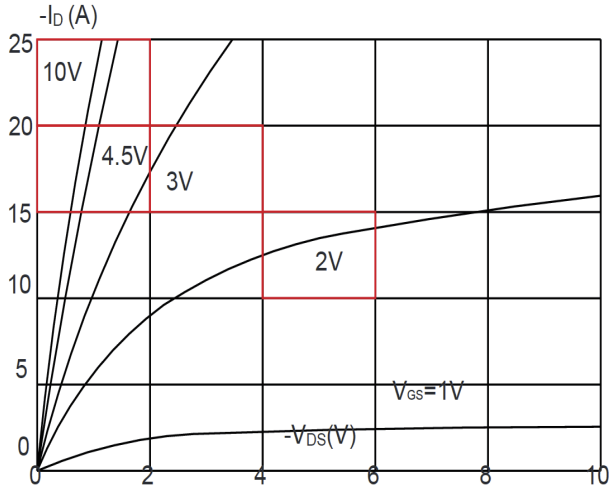


Figure 2: Typical Transfer Characteristics

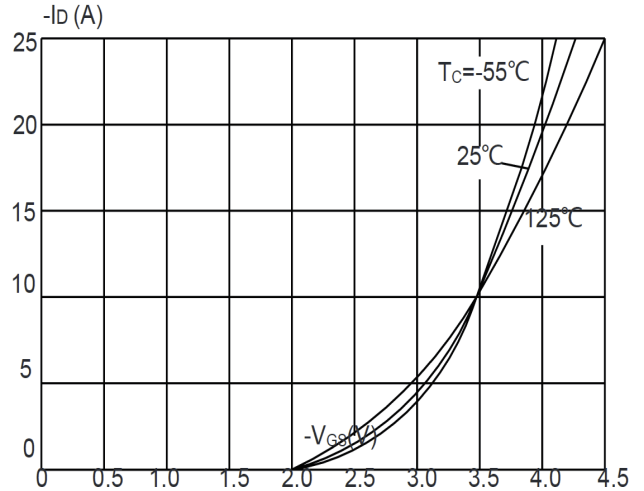


Figure 3: On-resistance vs. Drain Current

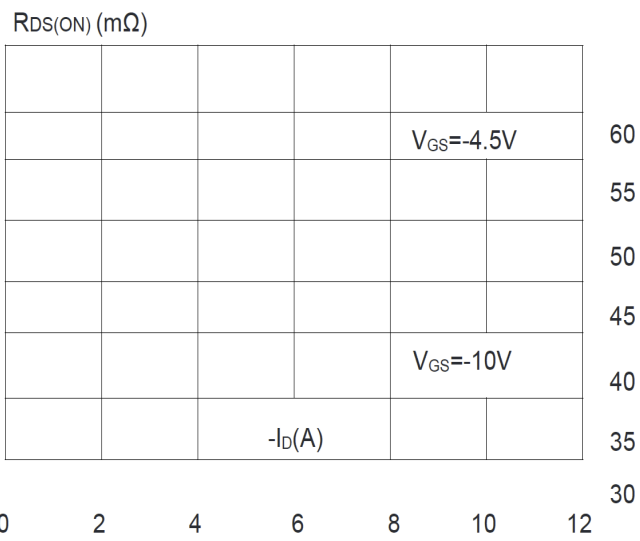


Figure 4: Body Diode Characteristics

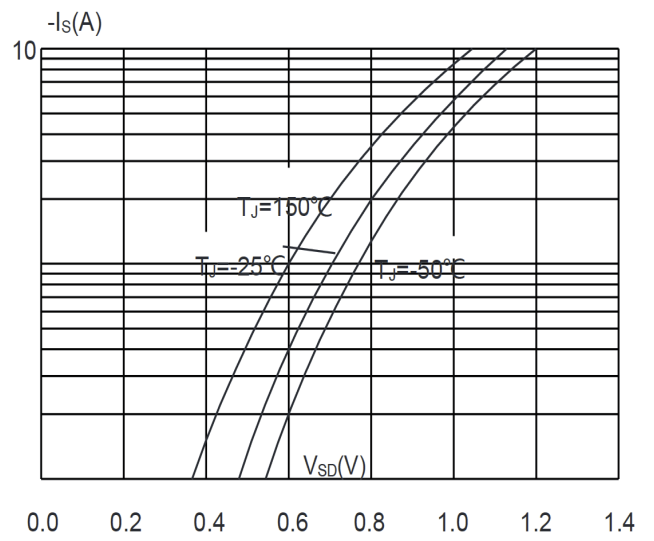


Figure 5: Gate Charge Characteristics

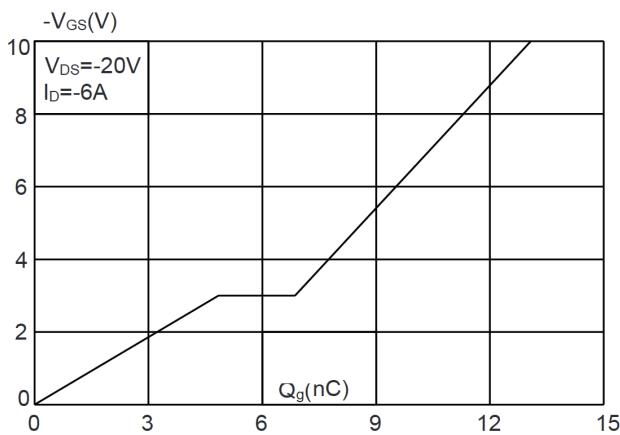
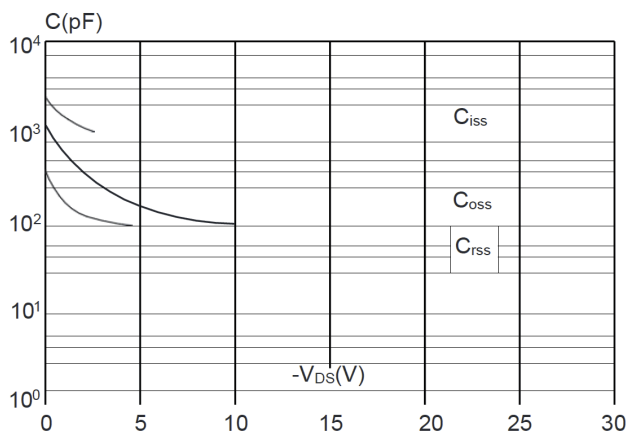


Figure 6: Capacitance Characteristics



P-Channel Typical Performance Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

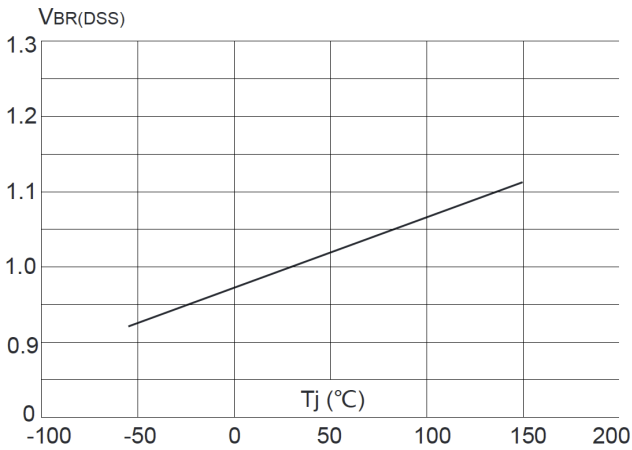


Figure 8: Normalized on Resistance vs. Junction Temperature

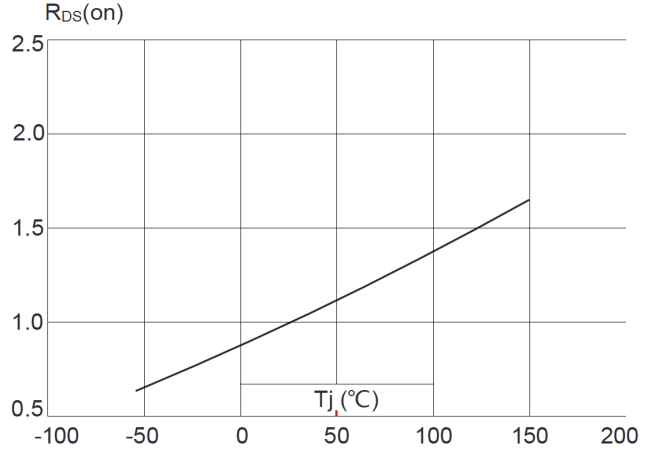


Figure 9: Maximum Safe Operating Area

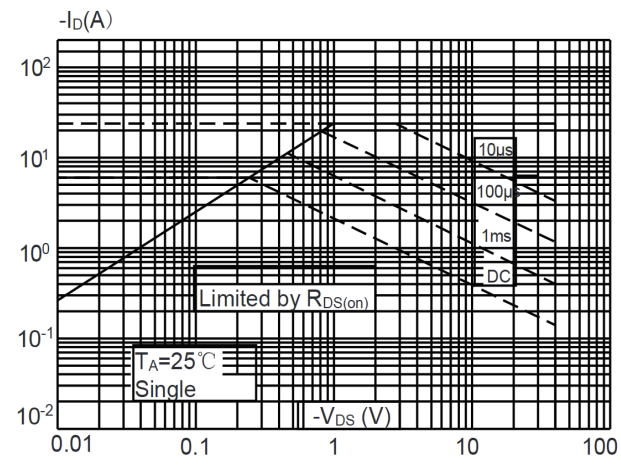


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

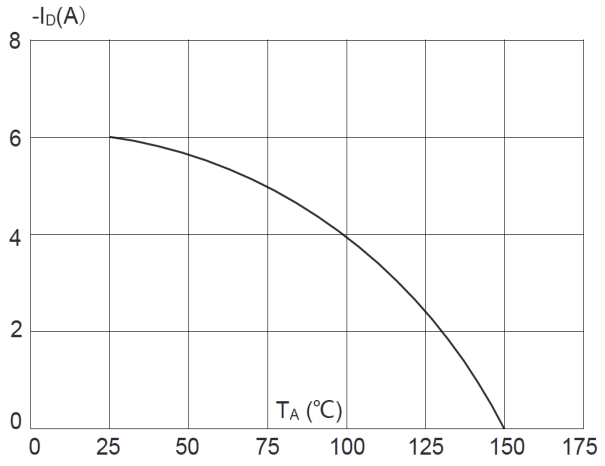
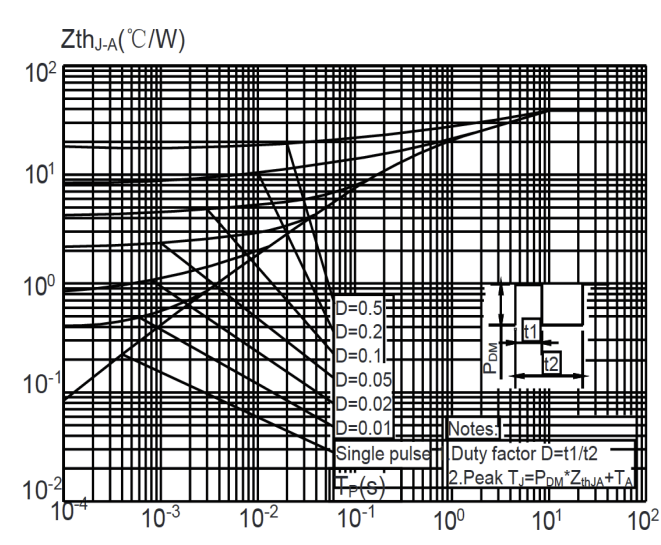
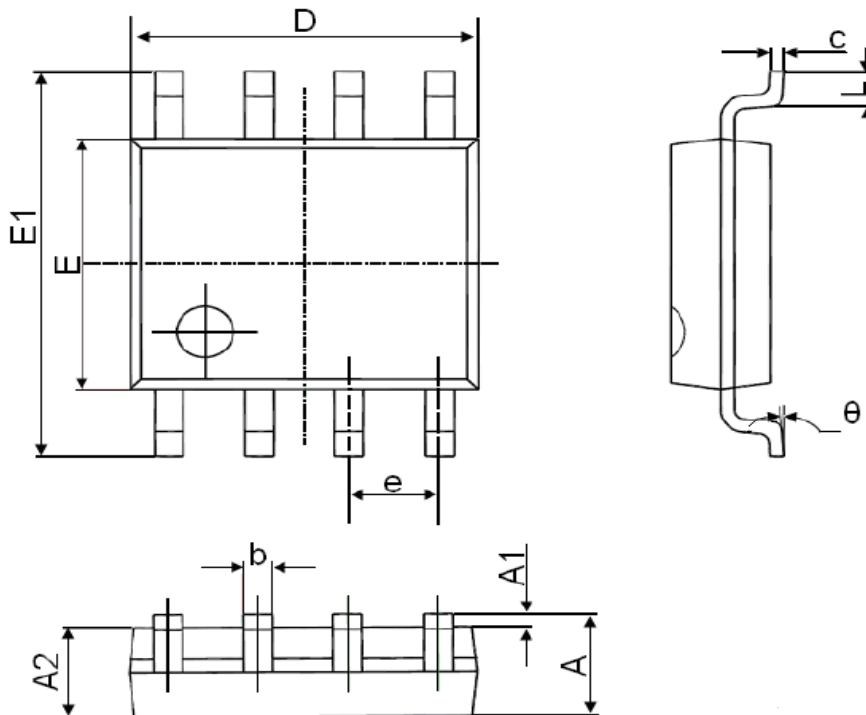


Figure 11: Maximum Effective Transient Thermal Impedance



Package Mechanical Data- SOP-8


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°